PRELIMINARY

CY7C1041G
CY7C1041GE

4-Mbit (256K words × 16 bit) Static RAM with Error-Correcting Code (ECC)

Features

- High speed
  - t_{AA} = 10 ns
- Embedded ECC for single-bit error correction[1]
- Low active and standby currents
  - Active current: I_{CC} = 38-mA typical
  - Standby current: I_{SB2} = 6-mA typical
- Operating voltage range: 1.65 V to 2.2 V, 2.2 V to 3.6 V, and 4.5 V to 5.5 V
- 1.0-V data retention
- TTL-compatible inputs and outputs
- Error indication (ERR) pin to indicate 1-bit error detection and correction
- Pb-free 44-pin SOJ, 44-pin TSOP II, and 48-ball VFBGA packages

Functional Description

CY7C1041G and CY7C1041GE are high-performance CMOS fast static RAM devices with embedded ECC. Both devices are offered in single and dual chip-enable options and in multiple pin configurations. The CY7C1041GE device includes an ERR pin that signals an error-detection and correction event during a read cycle.

Data writes are performed by asserting the Chip Enable ($\overline{CE}$) and Write Enable ($\overline{WE}$) inputs LOW, while providing the data on I/O_0 through I/O_{15} and address on A_0 through A_{17} pins. The Byte High Enable ($\overline{BHE}$) and Byte Low Enable ($\overline{BLE}$) inputs control write operations to the upper and lower bytes of the specified memory location. $\overline{BHE}$ controls I/O_8 through I/O_{15} and $\overline{BLE}$ controls I/O_0 through I/O_7.

Data reads are performed by asserting the Chip Enable ($\overline{CE}$) and Output Enable ($\overline{OE}$) inputs LOW and providing the required address on the address lines. Read data is accessible on the I/O lines (I/O_0 through I/O_{15}). Byte accesses can be performed by asserting the required byte enable signal ($\overline{BHE}$ or $\overline{BLE}$) to read either the upper byte or the lower byte of data from the specified address location.

All I/Os (I/O_0 through I/O_{15}) are placed in a high-impedance state during the following events:

- The device is deselected ($\overline{CE}$ HIGH)
- The control signals ($\overline{OE}$, $\overline{BLE}$, $\overline{BHE}$) are de-asserted

On the CY7C1041GE devices, the detection and correction of a single-bit error in the accessed location is indicated by the assertion of the ERR output (ERR = HIGH)[1]. See the Truth Table on page 14 for a complete description of read and write modes.

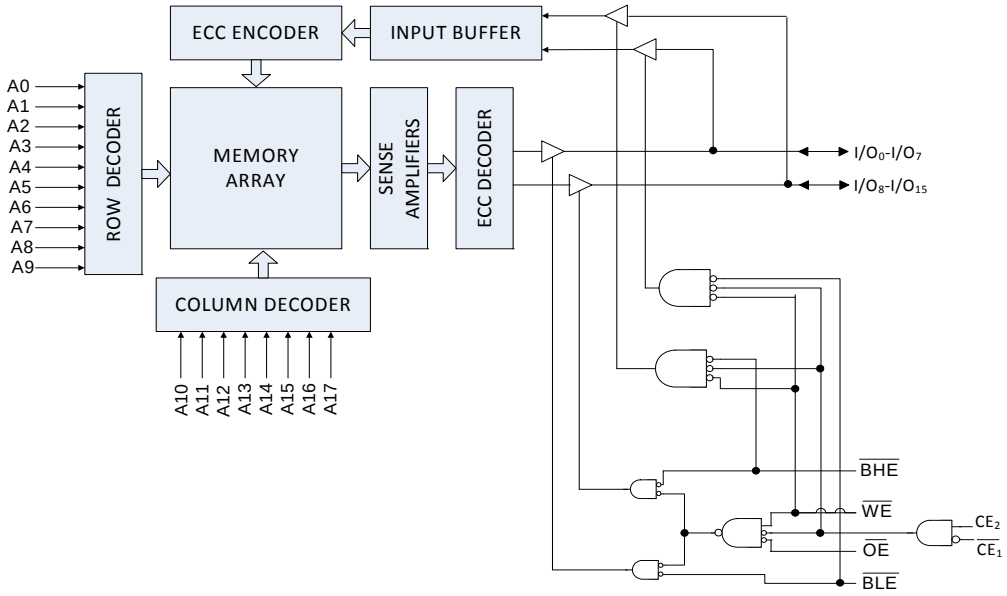
The logic block diagram is on page 2.

Product Portfolio

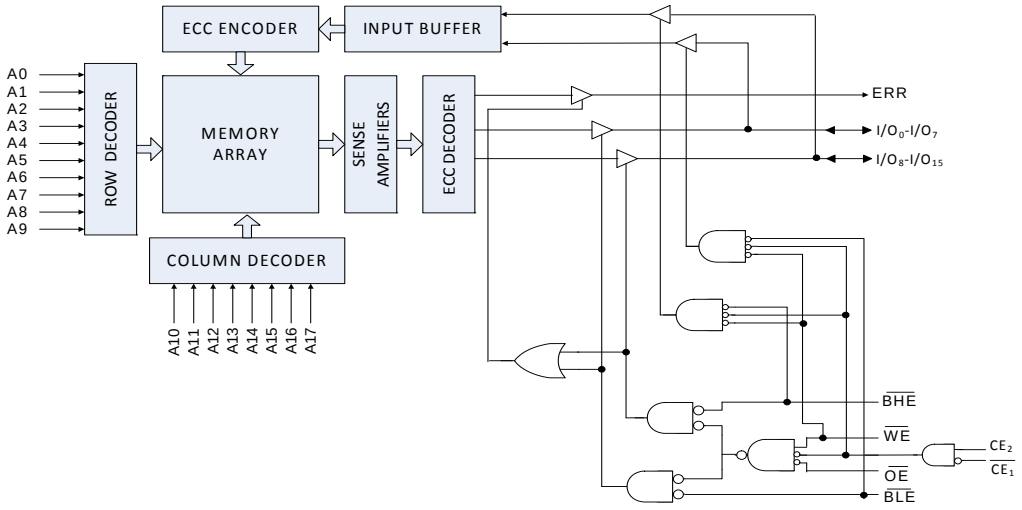
Product[2]	Features and Options (see Pin Configurations on page 4)	Range	V_{CC} Range (V)	Speed (ns) 10/15	Power Dissipation			
					Operating I_{CC}, (mA) f = f_{max}		Standby, I_{SB2} (mA)	
					Typ[3]	Max	Typ[3]	Max
CY7C1041G(E)18	Single or Dual Chip Enables	Industrial	1.65 V–2.2 V	15	–	40	6	8
CY7C1041G(E)30	Optional ERR pins		2.2 V–3.6 V	10	38	45		
CY7C1041G(E)			4.5 V–5.5 V	10	38	45		

Notes
1. This device does not support automatic write-back on error detection.
2. The ERR pin is available only for devices which have ERR option “E” in the ordering code. Refer Ordering Information for details
3. Typical values are included only for reference and are not guaranteed or tested. Typical values are measured at V_{CC} = 1.8 V (for a V_{CC} range of 1.65 V–2.2 V), V_{CC} = 3 V (for a V_{CC} range of 2.2 V–3.6 V), and V_{CC} = 5 V (for a V_{CC} range of 4.5 V–5.5 V), T_A = 25 °C.

Logic Block Diagram – CY7C1041G



Logic Block Diagram – CY7C1041GE



Contents

Pin Configurations

Figure 1. 48-ball VFBGA (6 × 8 × 1.0 mm) Single Chip Enable without ERR,CY7C1041G[4] Package/Grade ID: BVXI[6]

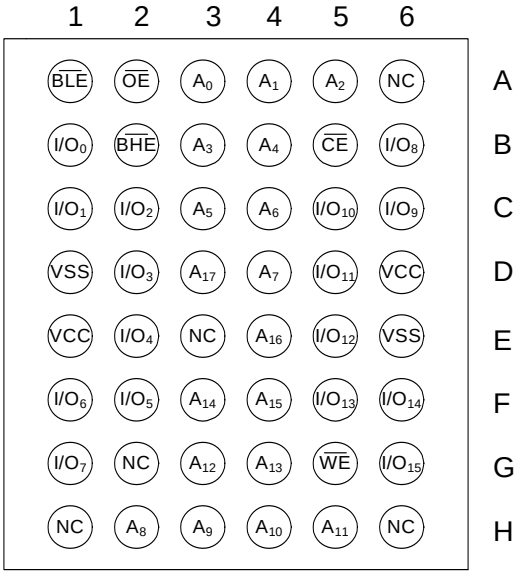


Figure 2. 48-ball VFBGA (6 × 8 × 1.0 mm) Single Chip Enable with ERR, CY7C1041GE[4,5] Package/Grade ID: BVXI[6]

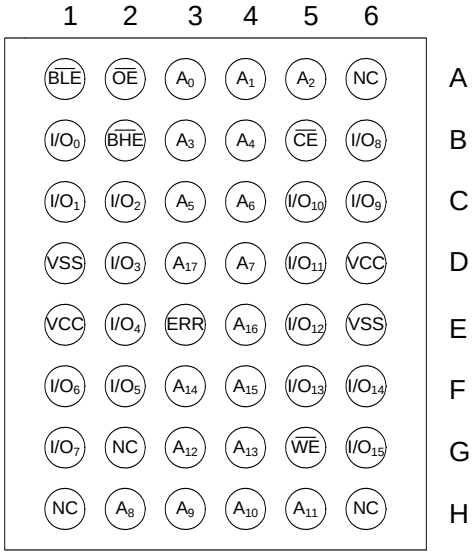


Figure 3. 48-ball VFBGA (6 × 8 × 1.0 mm) Single Chip Enable without ERR, CY7C1041G[4] Package/Grade ID: BVJXI[6]

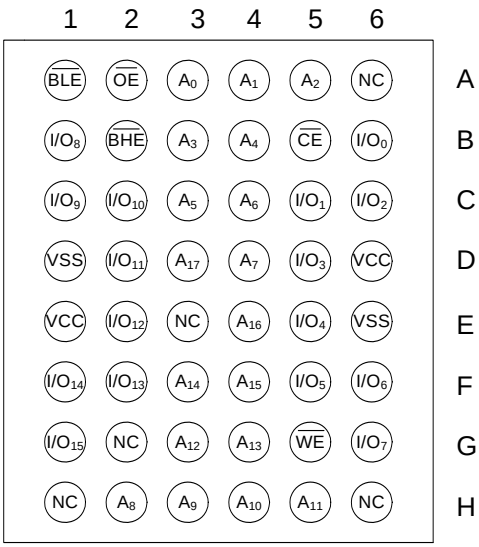
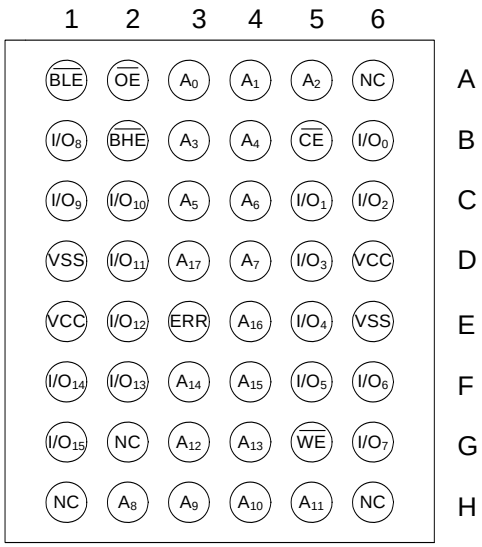


Figure 4. 48-ball VFBGA (6 × 8 × 1.0 mm) Single Chip Enable with ERR, CY7C1041GE[4, 5] Package/Grade ID: BVJXI[6]



Notes

4. NC pins are not connected internally to the die.
5. ERR is an output pin.
6. Package type BVJXI is JEDEC compliant compared to package type BVXI. The difference between the two is that the higher and lower byte I/Os ($I/O_{[7:0]}$ and $I/O_{[15:8]}$ balls are swapped.

Pin Configurations (continued)

Figure 5. 44-pin TSOP II/44-pin SOJ Single Chip Enable with ERR CY7C1041GE[7, 8]

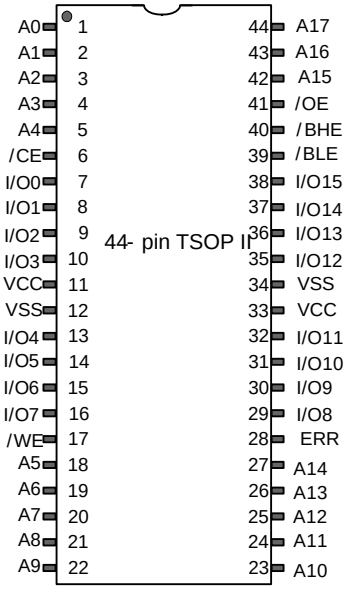
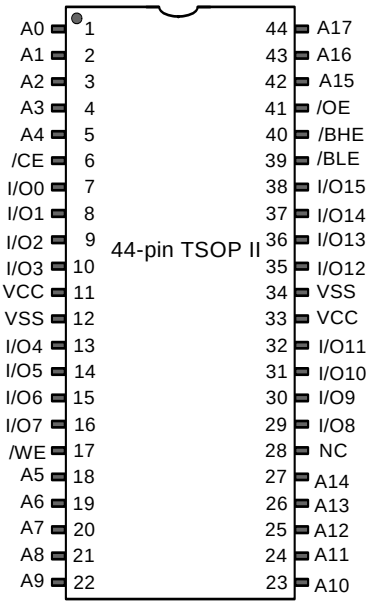


Figure 6. 44-pin TSOP II/44-pin SOJ Single Chip Enable without ERR CY7C1041G[7]



Notes
7. NC pins are not connected internally to the die.
8. ERR is an output pin.

Maximum Ratings

Exceeding maximum ratings may impair the useful life of the device. These user guidelines are not tested.

Storage temperature ..... –65 °C to +150 °C

Ambient temperature with power applied ..... –55 °C to +125 °C

Supply voltage on V_{CC} relative to GND[9] ..... –0.5 V to V_{CC} + 0.5 V

DC voltage applied to outputs in HI-Z State[9] ..... –0.5 V to V_{CC} + 0.5 V

DC input voltage [9] ..... –0.5 V to V_{CC} + 0.5 V

Current into outputs (in LOW state) ..... 20 mA

Static discharge voltage (MIL-STD-883, Method 3015) ..... > 2001 V

Latch-up current ..... > 140 mA

Operating Range

Grade	Ambient Temperature	V_{CC}
Industrial	–40 °C to +85 °C	1.65 V to 2.2 V, 2.2 V to 3.6 V, 4.5 V to 5.5 V

DC Electrical Characteristics

Over the operating range of –40 °C to 85 °C

Parameter	Description		Test Conditions		10 ns / 15 ns			Unit
					Min	Typ[10]	Max	
V_{OH}	Output HIGH voltage	1.65 V to 2.2 V	V_{CC} = Min, I_{OH} = –0.1 mA		1.4	–	–	V
		2.2 V to 2.7 V	V_{CC} = Min, I_{OH} = –1.0 mA		2	–	–	
		2.7 V to 3.6 V	V_{CC} = Min, I_{OH} = –4.0 mA		2.2	–	–	
		4.5 V to 5.5 V	V_{CC} = Min, I_{OH} = –4.0 mA		2.4	–	–	
		4.5 V to 5.5 V	V_{CC} = Min, I_{OH} = –0.1 mA		V_{CC}-0.5[11]	–	–	
V_{OL}	Output LOW voltage	1.65 V to 2.2 V	V_{CC} = Min, I_{OL} = 0.1 mA		–	–	0.2	V
		2.2 V to 2.7 V	V_{CC} = Min, I_{OL} = 2 mA		–	–	0.4	
		2.7 V to 3.6 V	V_{CC} = Min, I_{OL} = 8 mA		–	–	0.4	
		4.5 V to 5.5 V	V_{CC} = Min, I_{OL} = 8 mA		–	–	0.4	
V_{IH}	Input HIGH voltage	1.65 V to 2.2 V	–		1.4	–	V_{CC} + 0.2[9]	V
		2.2 V to 2.7 V	–		2	–	V_{CC} + 0.3[9]	
		2.7 V to 3.6 V	–		2	–	V_{CC} + 0.3[9]	
		4.5 V to 5.5 V	–		2.2	–	V_{CC} + 0.5[9]	
V_{IL}	Input LOW voltage	1.65 V to 2.2 V	–		–0.2[9]	–	0.4	V
		2.2 V to 2.7 V	–		–0.3[9]	–	0.6	
		2.7 V to 3.6 V	–		–0.3[9]	–	0.8	
		4.5 V to 5.5 V	–		–0.5[9]	–	0.8	
I_{IX}	Input leakage current		GND ≤ V_{IN} ≤ V_{CC}		–1	–	+1	µA
I_{OZ}	Output leakage current		GND ≤ V_{OUT} ≤ V_{CC}, Output disabled		–1	–	+1	µA
I_{CC}	Operating supply current		Max V_{CC}, I_{OUT} = 0 mA, CMOS levels	f = 100 MHz	–	38	45	mA
				f = 66.7 MHz	–	–	40	
I_{SB1}	Automatic CE power-down current – TTL inputs		Max V_{CC}, $\overline{CE}$ ≥ V_{IH}, V_{IN} ≥ V_{IH} or V_{IN} ≤ V_{IL}, f = f_{MAX}		–	–	15	mA
I_{SB2}	Automatic CE power-down current – CMOS inputs		Max V_{CC}, $\overline{CE}$ ≥ V_{CC} – 0.2 V, V_{IN} ≥ V_{CC} – 0.2 V or V_{IN} ≤ 0.2 V, f = 0		–	6	8	mA

Notes

9. $V_{IL(min)}$ = –2.0 V and $V_{IH(max)}$ = V_{CC} + 2 V for pulse durations of less than 2 ns.
10. Typical values are included for reference only and are not guaranteed or tested. Typical values are measured at V_{CC} = 1.8 V (for V_{CC} range of 1.65 V – 2.2 V), V_{CC} = 3 V (for V_{CC} range of 2.2V – 3.6 V), and V_{CC} = 5 V (for V_{CC} range of 4.5 V – 5.5 V), T_A = 25 °C.
11. This parameter is guaranteed by design and not tested.

Capacitance

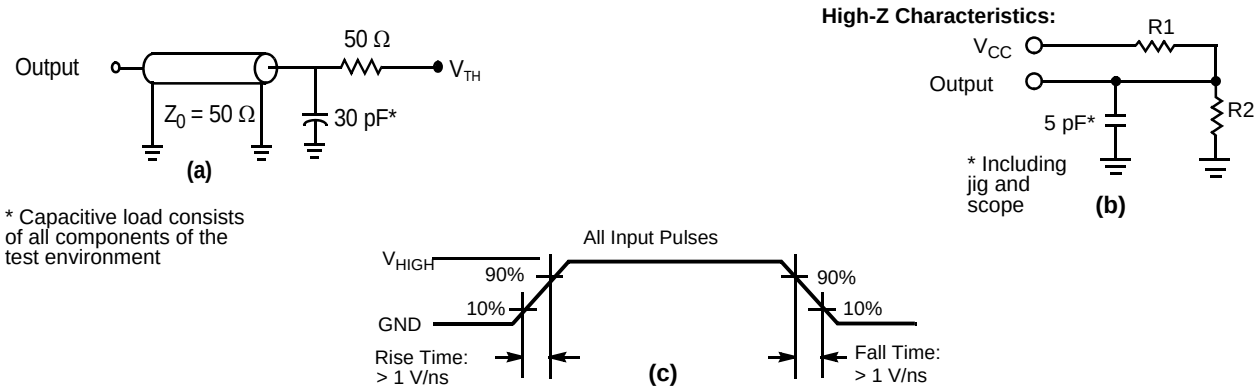
Parameter[12]	Description	Test Conditions	48-ball VFBGA	44-pin SOJ	44-pin TSOP II	Unit
C_{IN}	Input capacitance	T_A = 25 °C, f = 1 MHz, $V_{CC} = V_{CC(typ)}$	10	10	10	pF
C_{OUT}	I/O capacitance		10	10	10	pF

Thermal Resistance

Parameter[12]	Description	Test Conditions	48-ball VFBGA	44-pin SOJ	44-pin TSOP II	Unit
Θ_{JA}	Thermal resistance (junction to ambient)	Still air, soldered on a 3 × 4.5 inch, four layer printed circuit board	31.35	55.37	68.85	°C/W
Θ_{JC}	Thermal resistance (junction to case)		14.74	30.41	15.97	°C/W

AC Test Loads and Waveforms

Figure 7. AC Test Loads and Waveforms[13]



Parameters	1.8 V	3.0 V	5.0 V	Unit
R1	1667	317	317	Ω
R2	1538	351	351	Ω
V_{TH}	0.9	1.5	1.5	V
V_{HIGH}	1.8	3	3	V

Notes
12. Tested initially and after any design or process changes that may affect these parameters.
13. Full-device AC operation assumes a 100-µs ramp time from 0 to $V_{CC(min)}$ and a 100-µs wait time after V_{CC} stabilization.

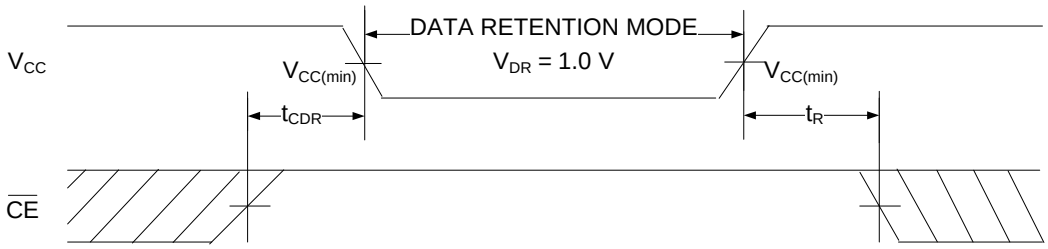
Data Retention Characteristics

Over the operating range of –40 °C to 85 °C

Parameter	Description	Conditions	Min	Max	Unit
V_{DR}	V_{CC} for data retention		1	–	V
I_{CCDR}	Data retention current	V_{CC} = 1.2 V, $\overline{CE} \geq V_{CC} - 0.2$ V[15], $V_{IN} \geq V_{CC} - 0.2$ V, or $V_{IN} \leq 0.2$ V	–	8	mA
t_{CDR}[14]	Chip deselect to data retention time		0	–	ns
t_R[14,15]	Operation recovery time	$V_{CC} \geq 2.2$ V	10	–	ns
		$V_{CC} < 2.2$ V	15	–	ns

Data Retention Waveform

Figure 8. Data Retention Waveform[15]



Notes
14. These parameters are guaranteed by design.
15. Full-device operation requires linear V_{CC} ramp from V_{DR} to $V_{CC(min)} \geq 100$ µs or stable at $V_{CC\ (min)} \geq 100$ µs.

AC Switching Characteristics

Over the operating range of –40 °C to 85 °C

Parameter[16]	Description	10 ns		15 ns		Unit
		Min	Max	Min	Max	
Read Cycle						
t_{RC}	Read cycle time	10	–	15	–	ns
t_{AA}	Address to data / ERR valid	–	10	–	15	ns
t_{OHA}	Data / ERR hold from address change	3	–	3	–	ns
t_{ACE}	$\overline{CE}$ LOW to data / ERR valid[17]	–	10	–	15	ns
t_{DOE}	$\overline{OE}$ LOW to data / ERR valid	–	4.5	–	8	ns
t_{LZOE}	$\overline{OE}$ LOW to low impedance[18, 19]	0	–	0	–	ns
t_{HZOE}	$\overline{OE}$ HIGH to HI-Z[18, 19]	–	5	–	8	ns
t_{LZCE}	$\overline{CE}$ LOW to low impedance[17, 18, 19]	3	–	3	–	ns
t_{HZCE}	$\overline{CE}$ HIGH to HI-Z[17, 18, 19]	–	5	–	8	ns
t_{PU}	$\overline{CE}$ LOW to power-up[17, 19, 20]	0	–	0	–	ns
t_{PD}	$\overline{CE}$ HIGH to power-down[17, 19, 20]	–	10	–	15	ns
t_{DBE}	Byte enable to data valid	–	4.5	–	8	ns
t_{LZBE}	Byte enable to low impedance[19]	0	–	0	–	ns
t_{HZBE}	Byte disable to HI-Z[19]	–	6	–	8	ns
Write Cycle[20, 21]						
t_{WC}	Write cycle time	10	–	15	–	ns
t_{SCE}	$\overline{CE}$ LOW to write end[17]	7	–	12	–	ns
t_{AW}	Address setup to write end	7	–	12	–	ns
t_{HA}	Address hold from write end	0	–	0	–	ns
t_{SA}	Address setup to write start	0	–	0	–	ns
t_{PWE}	$\overline{WE}$ pulse width	7	–	12	–	ns
t_{SD}	Data setup to write end	5	–	8	–	ns
t_{HD}	Data hold from write end	0	–	0	–	ns
t_{LZWE}	$\overline{WE}$ HIGH to low impedance[18, 19]	3	–	3	–	ns
t_{HZWE}	$\overline{WE}$ LOW to HI-Z[18, 19]	–	5	–	8	ns
t_{BW}	Byte Enable to write end	7	–	12	–	ns

Notes

16. Test conditions assume a signal transition time (rise/fall) of 3 ns or less, timing reference levels of 1.5 V (for $V_{CC} \geq 3$ V) and $V_{CC}/2$ (for $V_{CC} < 3$ V), and input pulse levels of 0 to 3 V (for $V_{CC} \geq 3$ V) and 0 to V_{CC} (for $V_{CC} < 3$ V). Test conditions for the read cycle use output loading, as shown in part (a) of Figure 7 on page 7, unless specified otherwise.
17. For all dual chip enable devices, $\overline{CE}$ is the logical combination of $\overline{CE}_1$ and CE_2. When $\overline{CE}_1$ is LOW and CE_2 is HIGH, $\overline{CE}$ is LOW; when $\overline{CE}_1$ is HIGH or CE_2 is LOW, $\overline{CE}$ is HIGH.
18. t_{HZOE}, t_{HZCE}, t_{HZWE}, t_{HZBE}, t_{LZOE}, t_{LZCE}, t_{LZWE}, and t_{LZBE} are specified with a load capacitance of 5 pF, as shown in part (b) of Figure 7 on page 7. Transition is measured ±200 mV from steady state voltage.
19. These parameters are guaranteed by design and are not tested.
20. The internal write time of the memory is defined by the overlap of $\overline{WE} = V_{IL}$, $\overline{CE} = V_{IL}$, and $\overline{BHE}$ or $\overline{BLE} = V_{IL}$. These signals must be LOW to initiate a write, and the HIGH transition of any of these signals can terminate the operation. The input data setup and hold timing should be referenced to the edge of the signal that terminates the write.
21. The minimum write cycle pulse width in write cycle No 2 ($\overline{WE}$ Controlled, $\overline{OE}$ low) should be equal to sum of t_{DS} and t_{HZWE}.

Switching Waveforms

Figure 9. Read Cycle No. 1 of CY7C1041G (Address Transition Controlled)[22, 23]

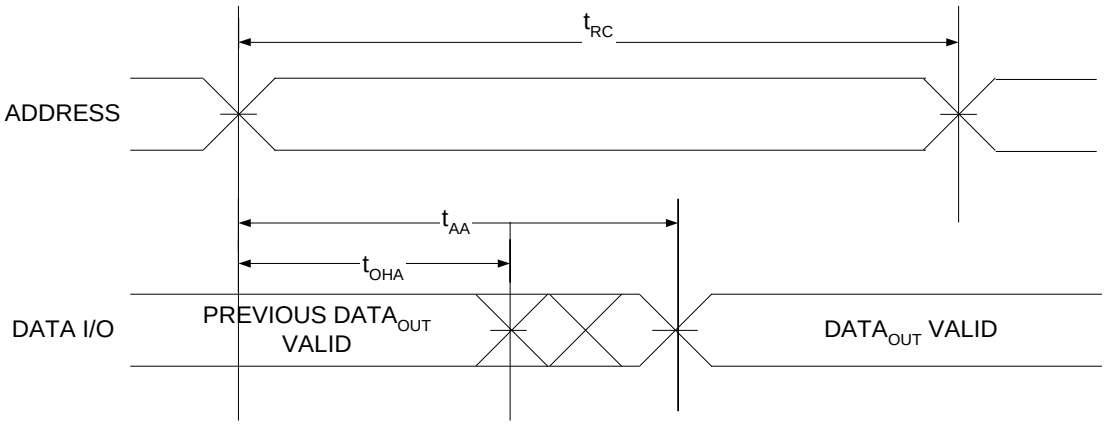
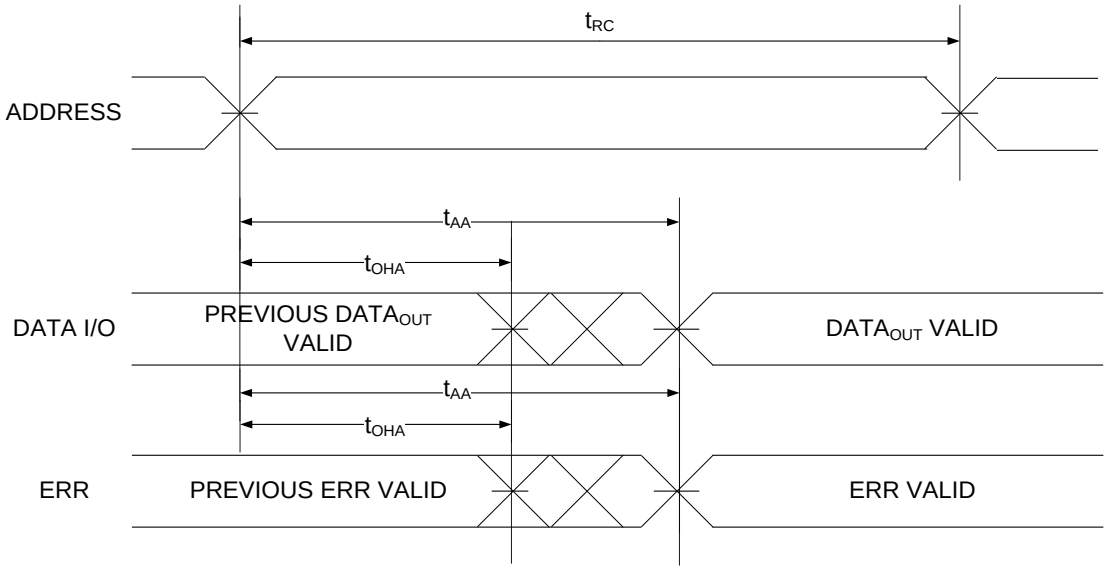


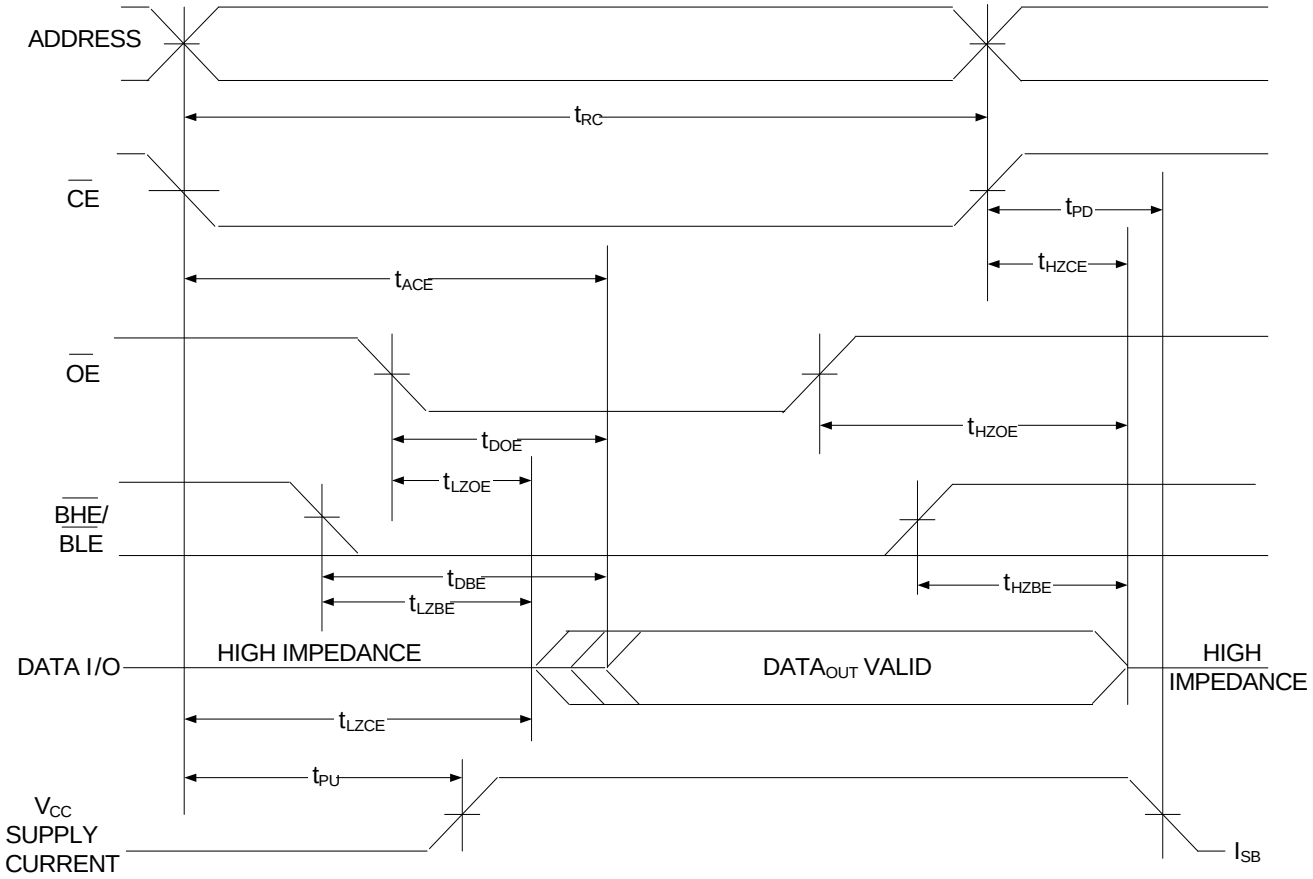
Figure 10. Read Cycle No. 1 of CY7C1041GE (Address Transition Controlled)[22, 23]



Notes
22. The device is continuously selected, $\overline{OE}$ = V_{IL}, $\overline{CE}$ = V_{IL}, $\overline{BHE}$ or $\overline{BLE}$ or both = V_{IL}.
23. $\overline{WE}$ is HIGH for the read cycle.

Switching Waveforms (continued)

Figure 11. Read Cycle No. 2 ($\overline{OE}$ Controlled)[24, 25, 26]



Notes

24. For all dual chip enable devices, $\overline{CE}$ is the logical combination of $\overline{CE}_1$ and CE_2. When $\overline{CE}_1$ is LOW and CE_2 is HIGH, $\overline{CE}$ is LOW; when $\overline{CE}_1$ is HIGH or CE_2 is LOW, $\overline{CE}$ is HIGH.
25. $\overline{WE}$ is HIGH for the read cycle.
26. Address valid prior to or coincident with $\overline{CE}$ LOW transition.

Switching Waveforms (continued)

Figure 12. Write Cycle No. 1 ($\overline{CE}$ Controlled)[27, 28, 29]

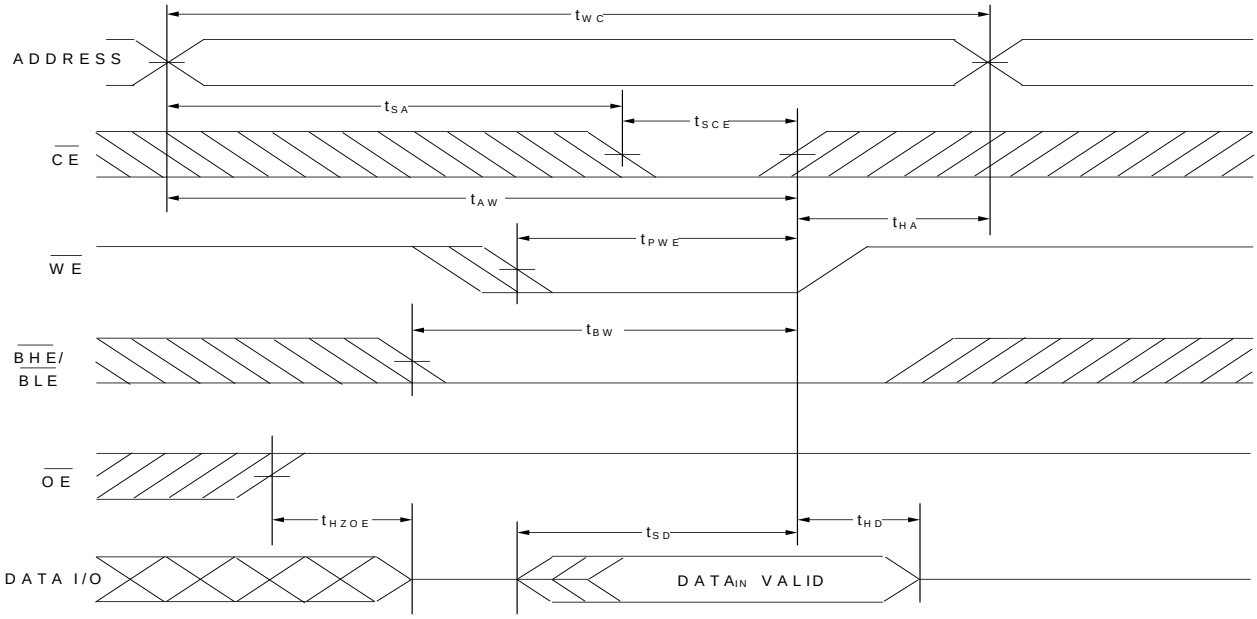
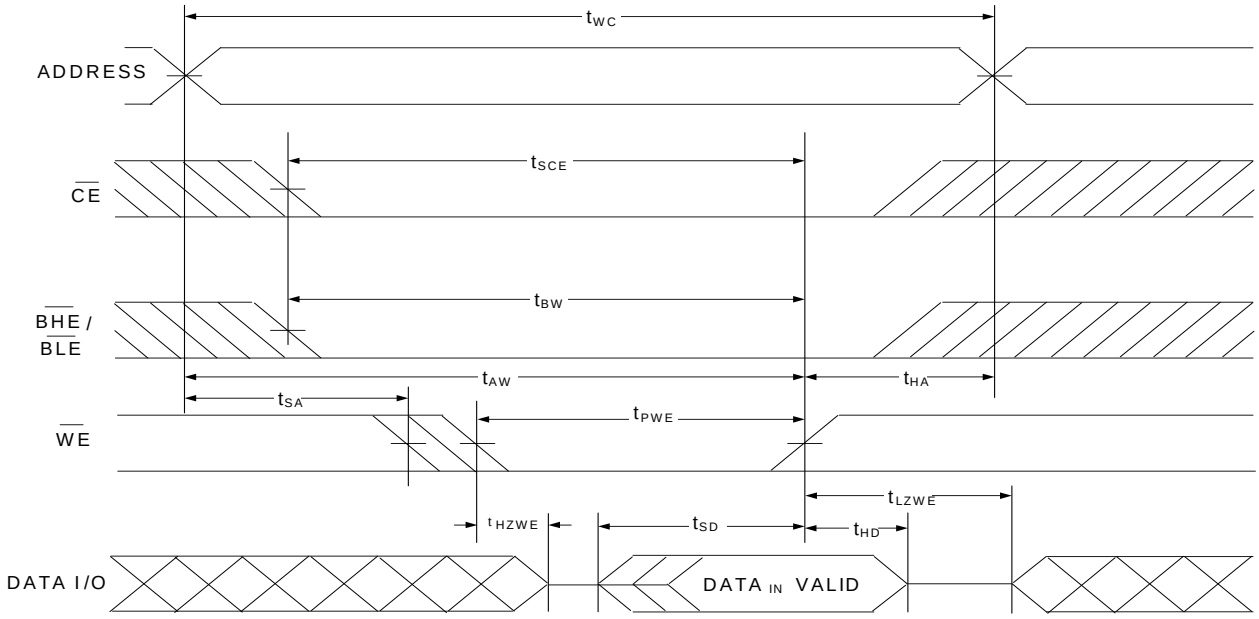


Figure 13. Write Cycle No. 2 ($\overline{WE}$ Controlled, $\overline{OE}$ LOW)[27, 28, 29, 30]



Notes

27. For all dual chip enable devices, $\overline{CE}$ is the logical combination of $\overline{CE}_1$ and CE_2. When $\overline{CE}_1$ is LOW and CE_2 is HIGH, $\overline{CE}$ is LOW; when $\overline{CE}_1$ is HIGH or CE_2 is LOW, $\overline{CE}$ is HIGH.
28. The internal write time of the memory is defined by the overlap of $\overline{WE}$ = V_{IL}, $\overline{CE}$ = V_{IL}, and $\overline{BHE}$ or $\overline{BLE}$ = V_{IL}. These signals must be LOW to initiate a write, and the HIGH transition of any of these signals can terminate the operation. The input data setup and hold timing should be referenced to the edge of the signal that terminates the write.
29. Data I/O is in HI-Z state if $\overline{CE}$ = V_{IH}, or $\overline{OE}$ = V_{IH}, or $\overline{BHE}$, and/or $\overline{BLE}$ = V_{IH}.
30. The minimum write cycle pulse width should be equal to sum of t_{SD} and t_{HZWE}.

Switching Waveforms (continued)

Figure 14. Write Cycle No. 3 (BLE or BHE Controlled)[31, 32, 33]

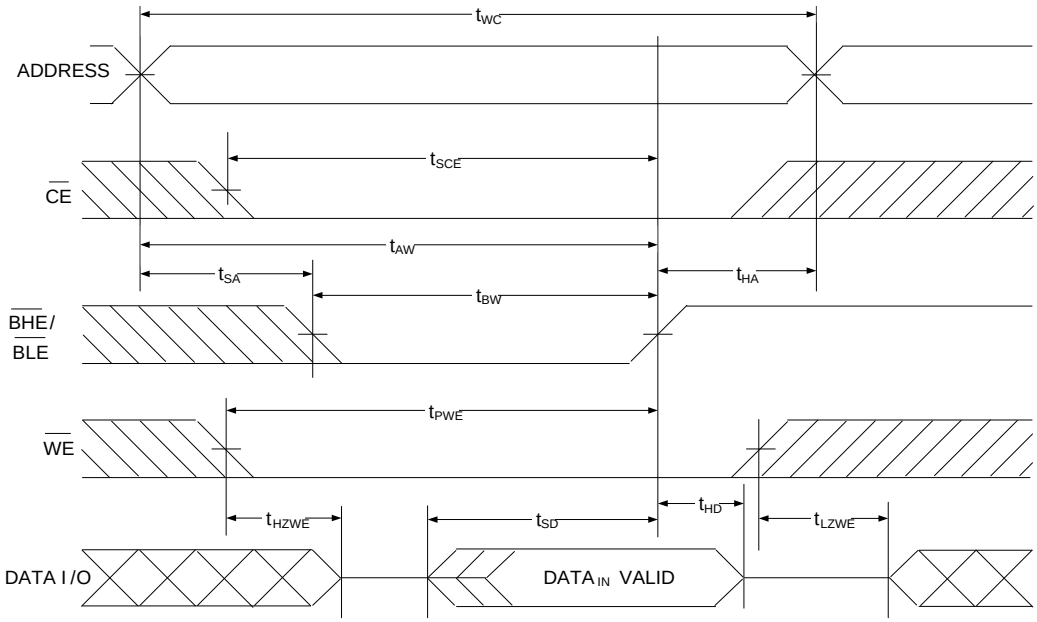
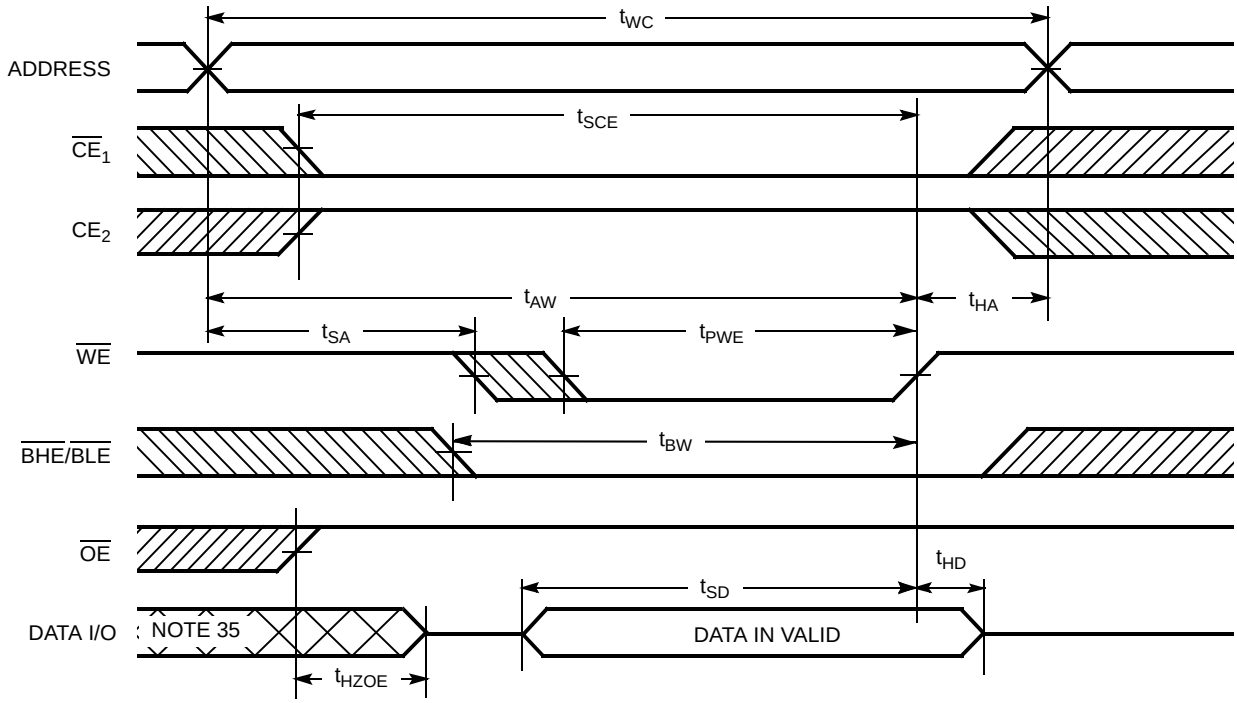


Figure 15. Write Cycle No. 4 (WE Controlled)[31, 32, 33, 34]



Notes

31. For all dual chip enable devices, $\overline{CE}$ is the logical combination of $\overline{CE}_1$ and CE_2. When $\overline{CE}_1$ is LOW and CE_2 is HIGH, $\overline{CE}$ is LOW; when $\overline{CE}_1$ is HIGH or CE_2 is LOW, $\overline{CE}$ is HIGH.
32. The internal write time of the memory is defined by the overlap of $\overline{WE}$ = V_{IL}, $\overline{CE}$ = V_{IL}, and $\overline{BHE}$ or $\overline{BLE}$ = V_{IL}. These signals must be LOW to initiate a write, and the HIGH transition of any of these signals can terminate the operation. The input data setup and hold timing should be referenced to the edge of the signal that terminates the write.
33. Data I/O is in HI-Z state if $\overline{CE}$ = V_{IH}, or $\overline{OE}$ = V_{IH}, or $\overline{BHE}$, and/or $\overline{BLE}$ = V_{IH}.
34. Data I/O is high impedance if $\overline{OE}$ = V_{IH}.
35. During this period the I/Os are in output state. Do not apply input signals.

Truth Table

$\overline{CE}$ [36]	$\overline{OE}$	$\overline{WE}$	$\overline{BLE}$	$\overline{BHE}$	I/O_0–I/O_7	I/O_8–I/O_{15}	Mode	Power
H	X[37]	X[37]	X[37]	X[37]	HI-Z	HI-Z	Power down	Standby (I_{SB})
L	L	H	L	L	Data out	Data out	Read all bits	Active (I_{CC})
L	L	H	L	H	Data out	HI-Z	Read lower bits only	Active (I_{CC})
L	L	H	H	L	HI-Z	Data out	Read upper bits only	Active (I_{CC})
L	X	L	L	L	Data in	Data in	Write all bits	Active (I_{CC})
L	X	L	L	H	Data in	HI-Z	Write lower bits only	Active (I_{CC})
L	X	L	H	L	HI-Z	Data in	Write upper bits only	Active (I_{CC})
L	H	H	X	X	HI-Z	HI-Z	Selected, outputs disabled	Active (I_{CC})

ERR Output – CY7C1041GE

Output[38]	Mode
0	Read operation, no single-bit error in the stored data.
1	Read operation, single-bit error detected and corrected.
HI-Z	Device deselected or outputs disabled or Write operation

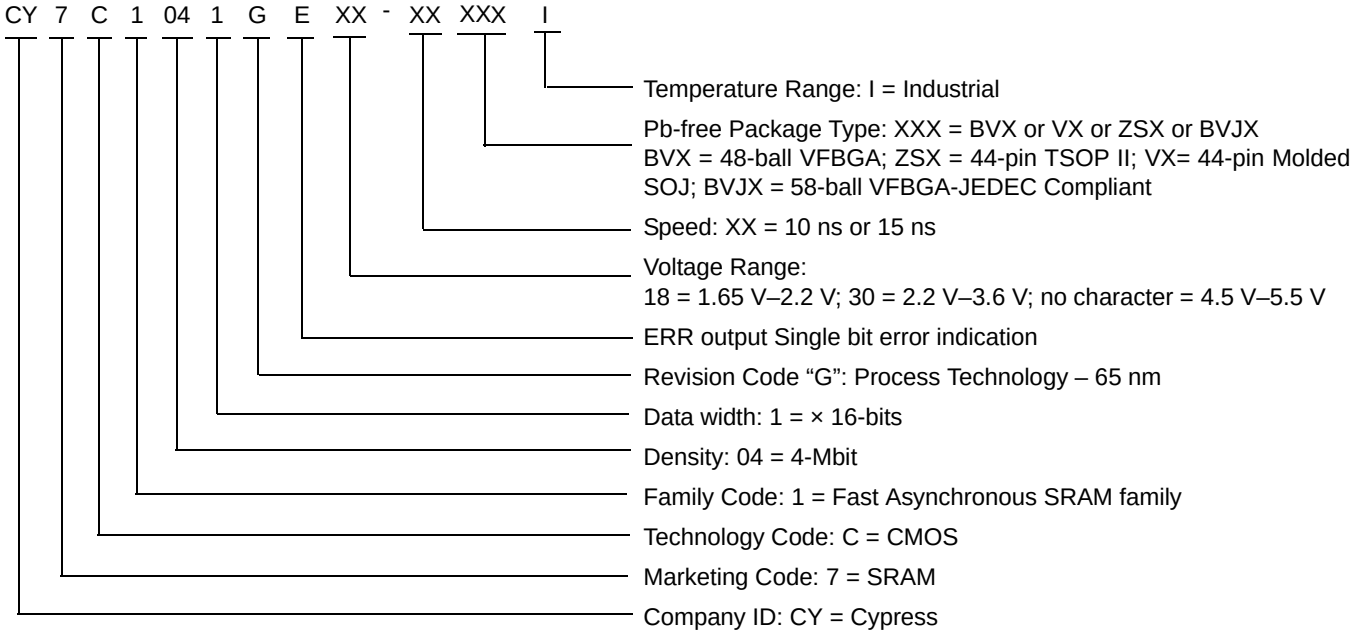
Notes

36. For all dual chip enable devices, $\overline{CE}$ is the logical combination of $\overline{CE}_1$ and CE_2. When $\overline{CE}_1$ is LOW and CE_2 is HIGH, $\overline{CE}$ is LOW; when $\overline{CE}_1$ is HIGH or CE_2 is LOW, $\overline{CE}$ is HIGH.
37. The input voltage levels on these pins should be either at V_{IH} or V_{IL}.
38. ERR is an Output pin.If not used, this pin should be left floating

Ordering Information

Speed (ns)	Voltage Range	Ordering Code	Package Diagram	Package Type (all Pb-free)	Operating Range
10	2.2 V–3.6 V	CY7C1041GE30-10VXI	51-85082	44-pin Molded SOJ, ERR output	Industrial
		CY7C1041G30-10VXI	51-85082	44-pin Molded SOJ	
		CY7C1041GE30-10ZSXI	51-85087	44-pin TSOP II, ERR output	
		CY7C1041G30-10ZSXI	51-85087	44-pin TSOP II	
		CY7C1041GE30-10BVXI	51-85150	48-ball VFBGA (6 × 8 × 1.0 mm), ERR output	
		CY7C1041G30-10BVXI	51-85150	48-ball VFBGA (6 × 8 × 1.0 mm)	
		CY7C1041GE30-10BVJXI	51-85150	48-ball VFBGA (6 × 8 × 1.0 mm), ERR output, JEDEC Compliant	
		CY7C1041G30-10BVJXI	51-85150	48-ball VFBGA (6 × 8 × 1.0 mm), JEDEC	
15	1.65 V–2.2 V	CY7C1041GE18-15VXI	51-85082	44-pin Molded SOJ, ERR output	
		CY7C1041G18-15VXI	51-85082	44-pin Molded SOJ	
		CY7C1041GE18-15ZSXI	51-85087	44-pin TSOP II, ERR output	
		CY7C1041G18-15ZSXI	51-85087	44-pin TSOP II	
		CY7C1041GE18-15BVXI	51-85150	48-ball VFBGA (6 × 8 × 1.0 mm), ERR output	
		CY7C1041G18-15BVXI	51-85150	48-ball VFBGA (6 × 8 × 1.0 mm)	
10	4.5 V–5.5 V	CY7C1041GE-10VXI	51-85087	44-pin Molded SOJ, ERR output	
		CY7C1041G-10VXI	51-85087	44-pin Molded SOJ	
		CY7C1041GE-10ZSXI	51-85087	44-pin TSOP II, ERR output	
		CY7C1041G-10ZSXI	51-85087	44-pin TSOP II	
		CY7C1041GE-10BVXI	51-85150	48-ball VFBGA (6 × 8 × 1.0 mm), ERR output	
		CY7C1041G-10BVXI	51-85150	48-ball VFBGA (6 × 8 × 1.0 mm)	

Ordering Code Definitions



Package Diagrams

Figure 16. 44-pin TSOP II (Z44) Package Outline, 51-85087

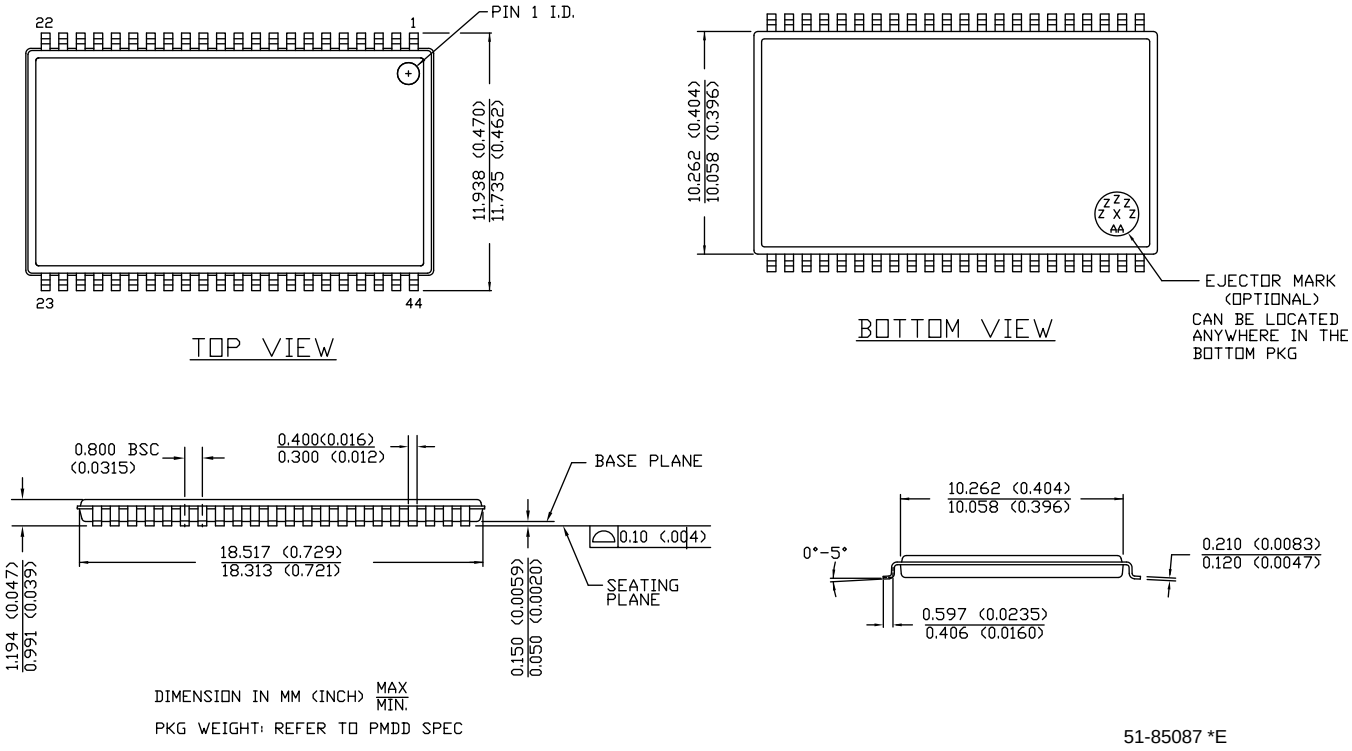
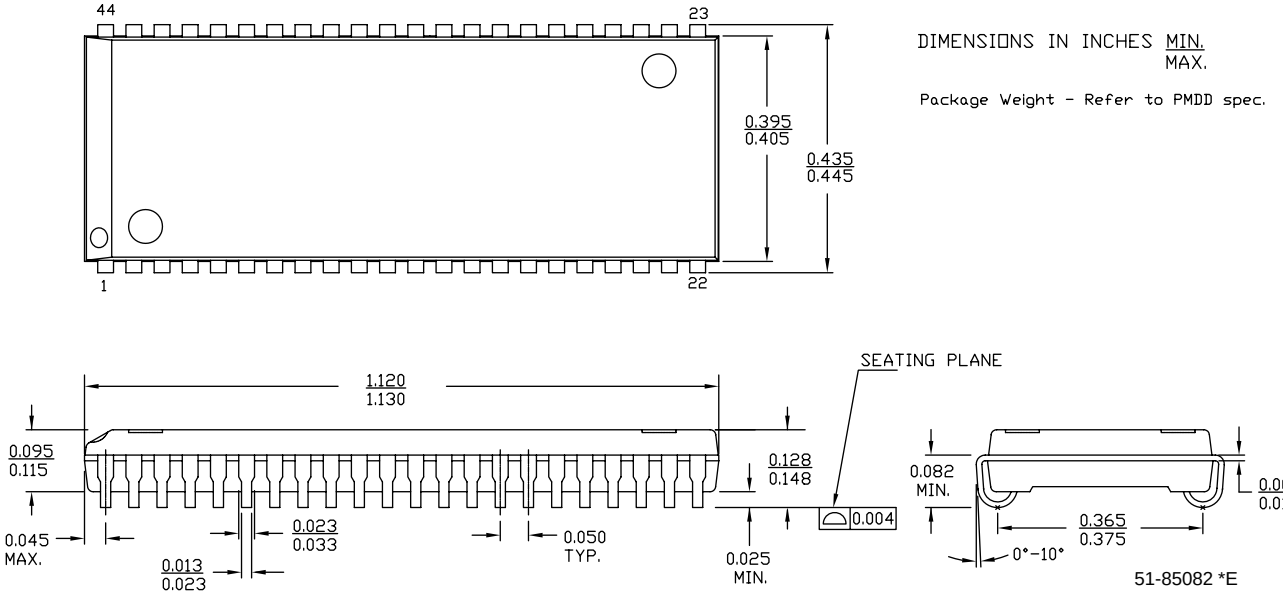
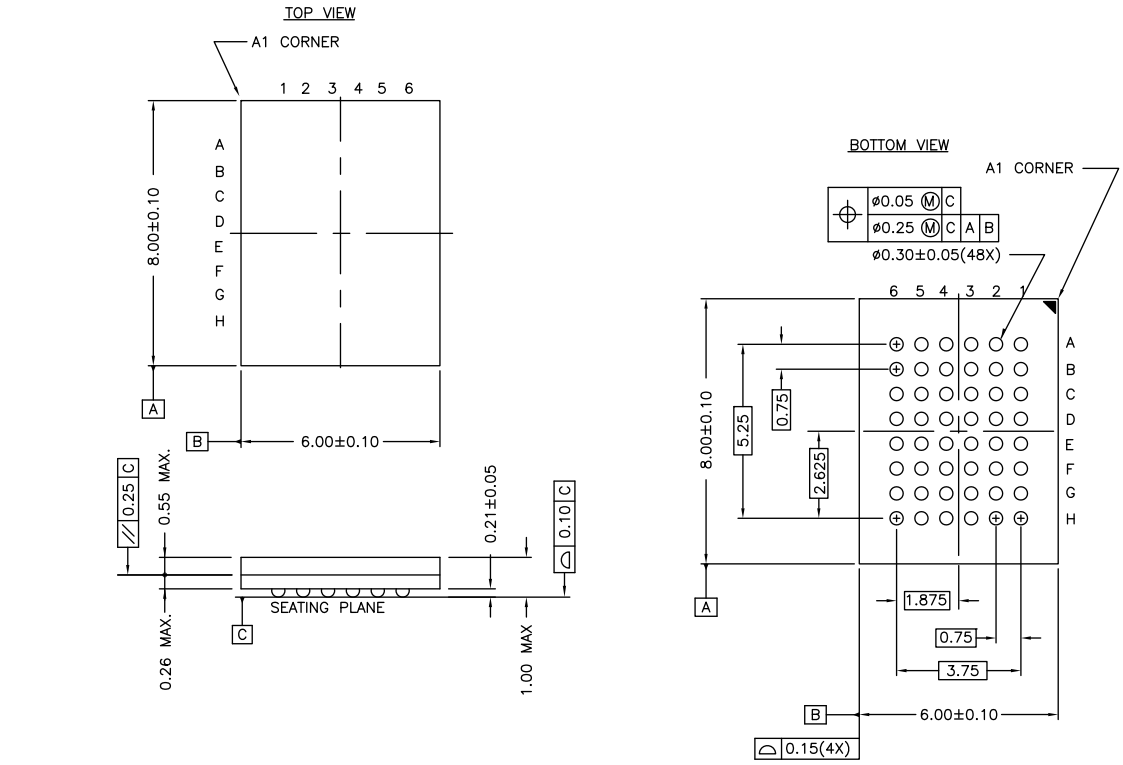


Figure 17. 44-Pin SOJ (400 Mils) Package Outline - 51-85082



Package Diagrams (continued)

Figure 18. 48-ball VFBGA (6 × 8 × 1.0 mm) BV48/BZ48 Package Outline, 51-85150



NOTE:
PACKAGE WEIGHT: See Cypress Package Material Declaration Datasheet (PMDD) posted on the Cypress web.

51-85150 *H

Acronyms

Acronym	Description
$\overline{\text{BHE}}$	Byte High Enable
$\overline{\text{BLE}}$	Byte Low Enable
$\overline{\text{CE}}$	Chip Enable
CMOS	Complementary Metal Oxide Semiconductor
I/O	Input/Output
$\overline{\text{OE}}$	Output Enable
SRAM	Static Random Access Memory
TSOP	Thin Small Outline Package
TTL	Transistor-Transistor Logic
VFBGA	Very Fine-Pitch Ball Grid Array
$\overline{\text{WE}}$	Write Enable

Document Conventions

Units of Measure

Symbol	Unit of Measure
°C	degrees Celsius
MHz	megahertz
µA	microampere
µs	microsecond
mA	milliampere
mm	millimeter
ns	nanosecond
Ω	ohm
%	percent
pF	picofarad
V	volt
W	watt

Document History Page

Document Title: CY7C1041G/CY7C1041GE, 4-Mbit (256K words × 16 bit) Static RAM with Error-Correcting Code (ECC) Document Number: 001-91368				
Rev.	**ECN No.**	**Orig. of Change**	**Submission Date**	**Description of Change**
**	4407441	SMCH/VINI	06/25/2014	New datasheet.
*A	4498947	SMCH	09/10/2014	Updated Figure 1 and Figure 3.
*B	4553979	SMCH	10/30/2014	Updated the Ordering Information Added $I_{CC(typ)}$ for the 5-V part in Product Portfolio as 38 mA
*C	4611296	NILE	12/31/2014	Updated the Ordering Information. Corrected Pin Configurations for JEDEC Compliant package and added Figure 3. Added footnotes 15 and 21. Updated Figure 11 through Figure 13.
*D	4710838	NILE	04/02/2015	Updated Thermal Resistance

Sales, Solutions, and Legal Information

Worldwide Sales and Design Support

Cypress maintains a worldwide network of offices, solution centers, manufacturer's representatives, and distributors. To find the office closest to you, visit us at Cypress Locations.

Products

Automotive	cypress.com/go/automotive
Clocks & Buffers	cypress.com/go/clocks
Interface	cypress.com/go/interface
Lighting & Power Control	cypress.com/go/powerpsoc
Memory	cypress.com/go/memory
PSoC	cypress.com/go/psoc
Touch Sensing	cypress.com/go/touch
USB Controllers	cypress.com/go/USB
Wireless/RF	cypress.com/go/wireless

PSoC® Solutions

psoc.cypress.com/solutions

PSoC 1 | PSoC 3 | PSoC 4 | PSoC 5LP

Cypress Developer Community

Community | Forums | Blogs | Video | Training

Technical Support

cypress.com/go/support

Общество с ограниченной ответственностью «МосЧип» ИНН 7719860671 / КПП 771901001
Адрес: 105318, г.Москва, ул.Щербаковская д.3, офис 1107

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

http://moschip.ru/get-element

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:
moschip.ru
moschip.ru_4
moschip.ru_6
moschip.ru_9